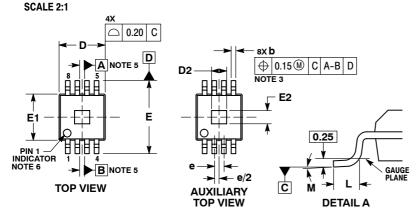
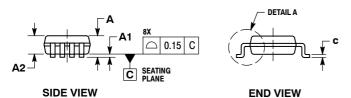
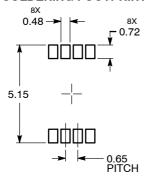


DATE 17 JUL 2009





RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

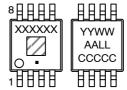
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION AND IS
- DETERMINED BETWEEN 0.08 AND 0.15 MM FROM THE LEAD TIP.
 DIMENSIONS D AND E1 DOES NOT INCLUDE MOLD
 PROTRUSIONS, TIE BAR BURRS, GATE BURRS OR FLASH. END
 FLASH SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D AND E1 DO INCLUDE ANY MOLD CAVITY MISMATCH AND ARE DETERMINED AT THE GAUGE PLANE.
- DATUMS A AND B TO BE DETERMINED AT THE GAUGE PLANE.
 DETAILS OF THE PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THIS ZONE.
 D2 AND E2 DIMENSIONS FOR TOP SIDE OF PACKAGE DENOTE
- SENSOR WINDOW SIZE AND LOCATION.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | | 1.10 | |
| A1 | 0.00 | 0.14 | |
| A2 | 0.73 | 0.93 | |
| b | 0.24 | 0.39 | |
| С | 0.13 | 0.24 | |
| D | 3.00 BSC | | |
| D2 | 0.66 | 1.37 | |
| E | 4.90 BSC | | |
| E1 | 3.00 BSC | | |
| E2 | 0.41 | 1.37 | |
| е | 0.65 BSC | | |
| L | 0.39 | 0.67 | |
| M | 0° | 8° | |

GENERIC MARKING DIAGRAM*

Top Mark Bottom Mark



XXXXX = Specific Device Code

YY = Year WW = Work Week AA= Assembly Location = Wafer Lot CCCCC = Country of Origin

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

= Pb-Free Package

| DOCUMENT NUMBER: | 98AON47771E | Electronic versions are uncontrolle | ' ' |
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| NEW STANDARD: | | | |
| DESCRIPTION: | CTSSOP8 3X3 WITH SENSOR WINDOW | I | PAGE 1 OF 2 |

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



| DOCUMENT | NUMBER: |
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